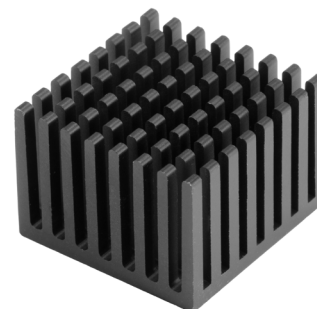




MODEL: HSB11-252518 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



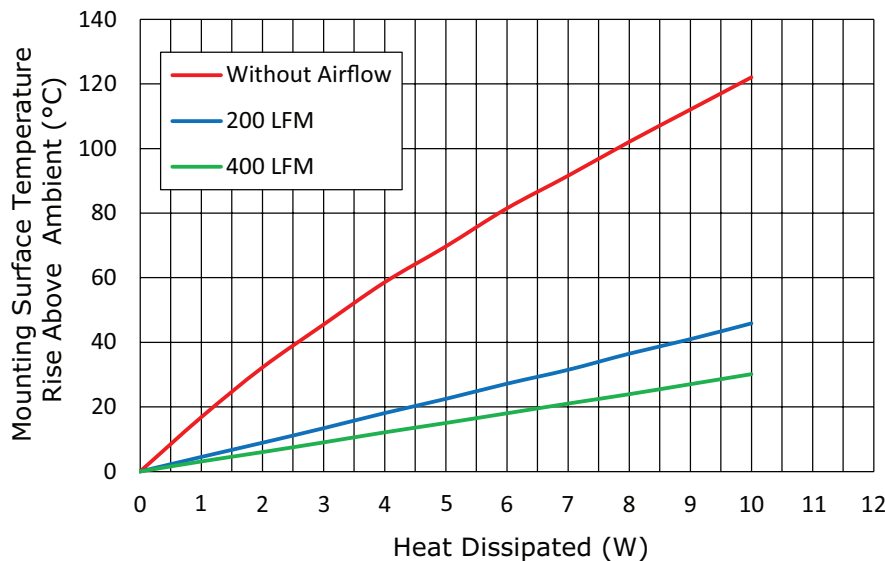
MODEL

| HSB11-252518 | thermal resistance ¹ | | | | power dissipation ¹ |
|--------------|---------------------------------|------------------------|-----------------------|-----------------------|--------------------------------|
| | @ 75°C ΔT, nat conv [°C/W] | @ 1 W, nat conv [°C/W] | @ 1 W, 200 LFM [°C/W] | @ 1 W, 400 LFM [°C/W] | @ 75°C ΔT, nat conv [W] |
| HSB11-252518 | 13.70 | 16.8 | 4.5 | 3.1 | 5.47 |

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

| Power (W) | Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C] | | |
|-----------|---|---------|---------|
| | Natural Conv. | 200 LFM | 400 LFM |
| 0 | 0 | 0 | 0 |
| 1 | 16.8 | 4.5 | 3.1 |
| 2 | 32.2 | 8.9 | 6.0 |
| 3 | 45.5 | 13.4 | 9.0 |
| 4 | 58.6 | 18.1 | 12.1 |
| 5 | 69.7 | 22.5 | 15.0 |
| 6 | 81.5 | 27.2 | 18.0 |
| 7 | 91.6 | 31.5 | 21.0 |
| 8 | 102.1 | 36.5 | 23.9 |
| 9 | 112.1 | 41.0 | 27.0 |
| 10 | 122.1 | 45.9 | 30.1 |



T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

CUI DEVICES | **MODEL:** HSB11-252518 | **DESCRIPTION:** HEAT SINK

MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

| | |
|----------|----------------|
| MATERIAL | AL 6063-T5 |
| FINISH | black anodized |
| WEIGHT | 12.5 g |

